INFORMATION DISCLOSURE		ATTY. DOCKET NO. SERIAL NO.					
1	CITATION	,	NTI-007-1D Filed Herewith				
PTO-1449		APPLICANT: Christophe Pierrat					
			FILING DATE: 9/9/2003	GR	OUP: unknow	m	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING	DATE
CVL	5,503,951	04/02/1996	Flanders et al.	430		04/17/1	995
CVL	5,565,286	10/15/1996	Lin	430		11/17/1	994
CVL	5,725,969	03/10/1998	Lee	430		12/22/1	995
CVL	6,004,702	12/21/1999	Lin	430		05/21/1	998
evi	6,010,807	01/04/2000	Lin	430		04/07/1	998
CVL	4,890,309	12/26/1989	Smith, et al.	378	35	02/25/1	987
CVL	5,288,569	2/22/1994	Lin	430	5	4/23/1992	
CVL	6,312,854 B1	11/6/2001	Chen, et al.	430	5	3/16/1999	
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CVL	WO 97/45772	12/4/1997	wo	 			
evl	WO 98/38549	9/3/1998	wo				
CVL	WO /99/27420	6/3/1999	wo				
CVL	WO 99/47981	9/23/1999	wo				
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	OTHER DO	CUMENTS (Including Author, Title, Date, P	ertinent P	ages, Etc.)	L	L.—.—
D CVL	Wong, A., et al.	, "Deep-UV-L	ithographic Approaches for 1Gh I al Papers, pp. 127-128 (1997).			n VLSI	
CVV	Chen, J. Fung, et al., "High-T, Ternary Attenuating PSMs for the 130mm Node", Microlithography World \ pp. 12, 14, 16, 18, 20 & 30 (2000).						
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
CVL	4,231,811	11/4/80	Somekh, et al.	148	1.5	9/13/79
en	4,456,371	6/26/84	Lin	355	71	6/30/82
CVL	4,812,962	3/14/89	Witt	364	490	4/9/87
CVL	4,902,899	2/20/90	Lin, et al.	250	492.1	6/1/87
CVL	5,051,598	9/24/91	Ashton, et al.	250	492.2	9/12/90
CVL	5,182,718	1/26/93	Harafuji, et al.	364	490	3/29/90
CVL	5,241,185	8/31/93	Meiri, et al.	250	492.2	1/8/92
CVL	5,242,770	9/7/93	Chen, et al.	430	5	1/16/92
CVL	5,256,505	10/26/93	Chen, et al.	430	5	8/21/92
CVL	5,302,477	4/12/94	Dao, et al.	430	5	8/21/92
CVL	5,308,741	5/3/94	Кетр	430	312	7/31/92
CVL	5,316,878	5/31/94	Saito, et al.	430	5	6/4/92
CVL	5,328,807	7/12/94	Tanaka, et al.	430	311	6/7/91
CVL	5,340,700	8/23/94	Chen, et al.	430	312	11/3/93
CVL	5,352,550	10/4/94	Okamoto	430	5	4/23/93
CVL	5,364,716	11/15/94	Nakagawa, et al.	430	5	9/3/92
CVL	5,424,154	6/13/95	Borodovsky	430	5	12/10/93
CVL	5,447,810	9/5/95	Chen, et al.	430	5	2/9/94
CVL	5,498,579	3/12/96	Borodovsky, et al.	437	250	6/8/94
CVL	5,523,186	6/4/96	Lin, et al.	430	5	12/16/94
OVL	5,532,090	7/2/96	Borodovsky	430	5	3/1/95
CVL	5,538,815	7/23/96	Oi, et al.	430	5	9/14/93
CVL	5,553,273	9/3/96	Liebmann	395	500	4/17/95
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
cvr	5,553,274	9/3/96	Liebmann	395	500	6/6/95
CVL	5,573,890	11/12/96	Spence	430	311	7/18/94
CVL	5,595,843	1/21/97	Dao	430	5	3/30/95
CVL	5,620,816	4/15/97	Dao	430	5	10/13/95
CVL	5,631,110	5/20/97	Shioiri, et al.	430	5	6/5/95
CVL	5,635,316	6/3/97	Dao	430	5	10/13/95
CVL	5,636,002	6/3/97	Garofalo	355	53	10/31/95
CVL	5,657,235	8/12/97	Liebmann, et al.	364	474.24	5/3/95
WL	5,663,017	9/2/97	Schinella, et al.	430	5	6/7/95
CVL	5,663,893	9/2/97	Wampler, et al.	364	491	5/3/95
CVL	5,702,848	12/30/97	Spence	430	5	8/23/96
evi	5,705,301	1/6/98	Garza, et al.	430	5	2/27/96
CVL	5,707,765	1/13/98	Chen	430	5	5/28/96
CVL	5,723,233	3/3/98	Garza, et al.	430	5	2/27/96
de	5,740,068	4/14/98	Liebmann, et al.	364	489	5/30/96
CN	5,761,075	6/2/98	Oi, et al.	364	488	5/31/96
CVL	5,766,804	6/16/98	Spence	430	5	8/23/96
CVL	5,766,806	6/16/98	Spence	430	5	9/9/96
CVL	5,807,649	9/15/98	Liebmann, et al.	430	5	10/31/96
OVL	5,815,685	9/29/98	Kamon	395	500	9/15/95
CVL	5,821,014	10/13/98	Chen, et al.	430	5	2/28/97
CVL	5,825,647	10/20/98	Tsudaka	364	167.03	3/12/96
CVL	5,827,623	10/27/98	Ishida, et al.	430	5	10/30/96
or	5,847,959	12/8/98	Veneklasen, et al.	364	468.28	1/28/97
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		U.S	. PATENT DOCUMENTS				
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cr	5,858,580	1/12/99	Wang, et al.	4:	30	5	9/17/97
CVL	5,862,058	1/19/99	Samuels, et al.	3(64	491	5/16/96
CVL	5,863,682	1/26/99	Abe, et al.	4:	30	30	2/21/97
CVL	5,879,844	3/9/99	Yamamoto, et al.	4:	30	30	12/20/96
ovu	5,885,734	3/23/99	Pierrat, et al.	4.	30	5	8/15/96
CVL	5,900,338	5/4/99	Garza, et al.	4:	30	5	8/15/97
CVL	5,923,566	6/13/99	Galan, et al.	30	54	489	3/25/97
CVL	5,994,002	11/30/99	Matsuoka	4.	30	5	9/4/97
cir	6,077,310	6/20/00	Yamamoto, et al.	7	16	19	1/29/99
CVL	6,078,738	6/20/00	Garza, et al.	39	95	500.22	5/8/97
CVL	6,081,658	6/27/00	Rieger, et al.	39	95	500.22	12/31/97
CVV	6,083,275	7/4/00	Heng, et al.	7	16	19	1/9/98
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cn	0 698 821	2/28/96	EPO	-			
cn	2,638,561	4/25/97	ЛР	 			1
CVL	2,650,962	5/16/97	JР	 -			
or	3-210560	9/13/91	JP	1			
ove	7-111528	2/14/91	JP				
OVL	8-236317	9/6/96	JP				
CVL	8-51068	2/20/96	JP	1			
CVL	10-133356	5/22/98	ЛР				
CVL	11-143085	5/28/99	JP				
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CVL	4,895,780	1/23/1990	Nissan-Cohen, et al.	430	5	10/25/1988
cvr	5,208,124	5/4/1993	Sporon-Fiedler, et al.	430	5	3/19/1991
CVL	5,324,600	6/28/1994	Jinbo, et al.	430	5	7/7/1992
CVZ	5,334,542	8/2/1994	Saito, et al.	437	40	11/18/1992
OVL	5,480,746	1/2/1996	linbo, et al.	430	5	5/16/1994
wi	5,496,666	3/5/1996	Chu, et al.	430	5	10/27/1994
ar	5,527,645	6/18/1996	Pati, et al.	430	5	11/17/1994
cv	5,537,648	7/16/1996	Liebmann, et al.	395	500	8/15/1994
cvi	5,539,568	7/23/1996	Lin, et al.	359	285	6/7/1995
CVL	5,636,131	6/3/1997	Liebmann, et al.	364	490	5/12/1995
cvc	5,682,323	10/28/1997	Pasch, et al.	364	491	3/6/1995
CVL	5,938,635	9/28/1999	Keich, et al.	430	30	10/20/1997
cve	5,972,541	10/26/1999	Sugasawara, et al.	430	5	3/4/1998
CUL	5,998,068	12/7/1999	Matsuoka	430	5	1/27/1998
eve	6,007,310	12/28/1999	Jacobsen, et al.	417	362	5/23/1997
CVL	6,057,063	5/2/2000	Liebmann, et al.	430	5	4/14/1997
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